

# Chaintech Technology Corporation

**Investment Forum** 

2019.12.16

# Declaration



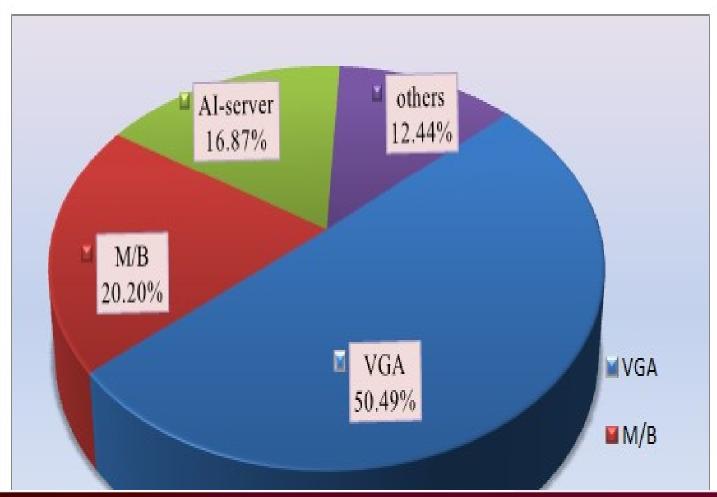
The information in this document won't contain financial forecasts.

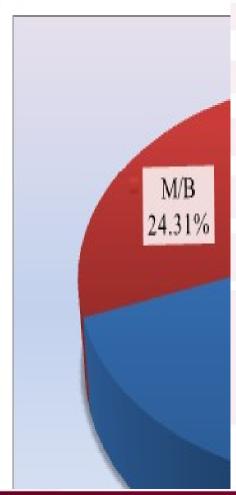
The information in this document was acquired from TSE MOPS and sources available to the company.

# Product Portfolio



2019/1/1-9/30







# Financial Statement

Statement of Comprehensive Income(QoQ)

CHAINTECH

Accounting Title	2019Q3 (7/1-9/30)	%	2019Q2 (4/1-6/3
Operating revenue	1,208,419	100.00	1,3:
Operating costs	1,131,089	93.60	1,22
Gross profit (loss) from operations	77,330	6.40	10
Operating expenses	60,271	4.99	
Net operating income	17,059	1.41	
Non-operating income and expenses	36,478	3.02	
Profit from continuing	53 537	1 13	a

# Statement of Comprehensive Income2019(YoY)

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Accounting Title	2019Q3 (7/1-9/30)	%	2018 (7/1-9)
Operating revenue	1,208,419	100.00	1,10
Operating costs	1,131,089	93.60	1,00
Gross profit (loss) from operations	77,330	6.40	9
Operating expenses	60,271	4.99	2
Net operating income	17,059	1.41	7
Non-operating income and expenses	36,478	3.02	
Profit from continuing operations before tax	53,537	4.43	7

## **2019Q3** Consolidated Condensed Balance Sheets-1

Accounting Title / Unit:KNTD	2019/9/30	%	2018/1
Cash and cash equivalents	609,402	22.34	652
financial assets at fair value through profit or loss-Current	2,010	0.07	
Accounts receivable, net	394,168	14.45	23'
Accounts receivable due from related parties, net	619,607	22.71	68:
other receivable	48,164	1.77	
inventories	521,379	19.11	9:
prepaid	35,988	1.32	2
Other current assets	74,481	2.73	32
Total current assets	2,305,199	84.50	1,72
financial assets at fair value through other comprehensive income-non-current	115,085	4.22	108

### 2018 Q3 Consolidated Condensed Balance Sheets-2

# CHAINTECH

Accounting Title / Unit:KNTD	2019/9/30	%	2018/12
Short-term loan	171,496	6.29	
Current contract liabilities	61,995	2.27	
Accounts payable	509,189	18.67	15
Accounts payabledue from related parties, net	16,756	0.61	
Other payables	64,122	2.35	6
Current tax liabilities	-	0.00	4
Current lease liabilities	9,700	0.36	
Other current liabilities	146	0.01	
Total current liabilities	833,404	30.55	27

### 2018 Q3 Consolidated Condensed Balance Sheets-3

## CHAINTECH

Accounting Title / Unit:KNTD	2019/9/30	%	2018/12
Deferred tax liabilities	10,518	0.39	
Non-current lease liabilities	1,366	0.05	
Other non-current liabilities	3,089	0.11	
Total non-current liabilities	14,973	0.55	
Total liabilities	848,377	31.10	28
capital stock	1,014,988	37.21	1,01
Legal reserve	122,290	4.48	9
Special reserve	112,514	4.12	8
Unappropriated retained earnings	560,196	20.54	64

# Financial Ratio



	2019.9.30	2018.12.31
Debt Ratio	31.10%	13.92%
Current Ratio	276.60%	619.59%
Quick Ratio	209.72%	584.66%
AR Turnover	5.21	4.08
Days sales in AR	70.05days	89.46days
Inventory Turnover	10.24	35.28
Average days in sales	35.64days	10.34days
Cash Flow Ratio	2.40%	159.19%

### Accounting Title / Unit:KNTD

Cash flows from operating activities
Profit (loss) from continuing operations before tax
Profit (loss) from discontinuing operations before tax

Profit (loss) before tax

### Adjustments

Depreciation expense Amortization expense

Expected credit loss (gain) / Provision (reversal of provision)

Net loss (gain) on financial assets or liabilities at fair value Interest expense

Interest income

Dividend income

Loss (gain) on disposal of property, plan and equipment Loss (gain) on disposal of non-current assets classified as held

### Changes in operating assets

Decreace (increace) in financial accete at fair value through

# Consolidated Condensed Cash Flow Statements

## Accounting Title / Unit:KNTD

2

### Changes in operating liabilities

Increase (decrease) in contract liabilities

Increase (decrease) in notes & accounts payable

Increase (decrease) in other payable

Increase (decrease) in other current liabilities

Cash inflow (outflow) generated from operations

Interest received

### Accounting Title / Unit:KNTD

20

### Cash flows from (used in) investing activities

Acquisition of financial assets at fair value through other comprehensive income

Increase in other non-current assets

Net cash flow from acquisition of subsidiaries

Proceeds from disposal of subsidiaries

Acquisition of property, plant and equipment

### Net cash flows from (used in) investing

### Cash flows from (used in) financing activities

Increase in short-term loans

Increase in guarantee deposits received

Decrease in guarantee deposits received

Payments of lease liabilities

Cash dividends paid



# 2020 Prospect

- Expand the AI server market continuously
- Application Technology Dep

Invest in software application technology

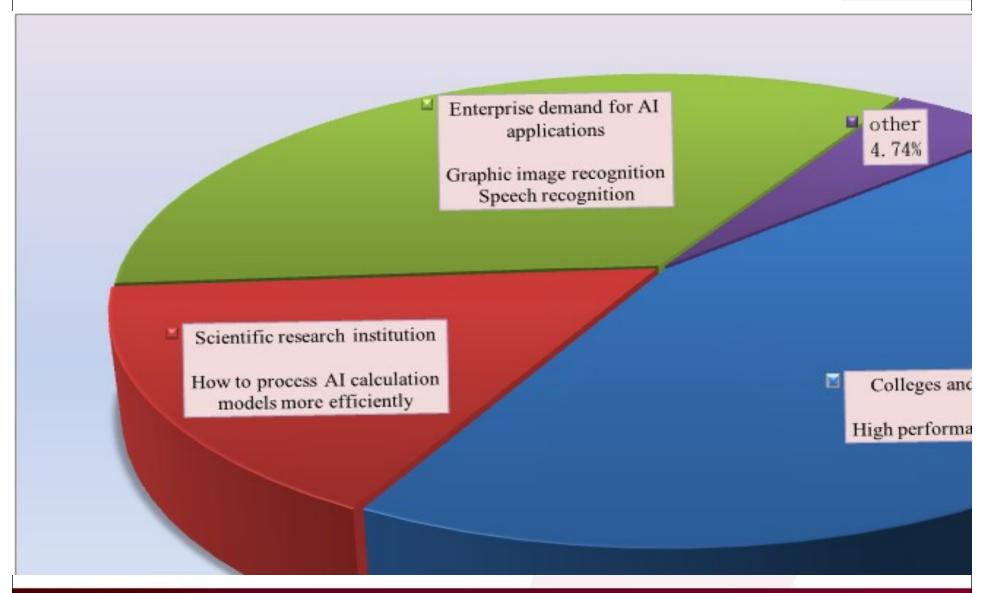
development and AI software and hardware

system integration continuously

# Invest in AI

Focus on AI SERVER SI & Application Technology









人工智能学院 School of Artificial Intelligence

XIDIAN UNIVERSITY -AI computing accele and technology-a computing acceleration platform project

### **Project background:**

XIDIAN UNIVERSITY is a national key university with information and electronic subjects as the main subject and coordinated development of engineering, science, management and culture. It is directly under the Ministry of education. It is one of the key universities of national advantageous discipline innovation platform project and "211 Project", one of the national innovation and entrepreneurship demonstration bases, the first 35 demonstration software colleges, the first nine demonstration microelectronics colleges and the first nine approved ones One of the first batch of demonstration projects for the construction of first-class network security college

Facing the major national strategic development and international cutting-edge development needs, the College of artificial intelligence of XIAN UNIVERSITY deeply implements the spirit of the report of the 19th National Congress and the development plan of new generation artificial intelligence, practices the construction of "Internet + belt and road" and innovation oriented country, and strives to build a training base for high-end talents in the field of artificial intelligence, a research and Development Center for innovation achievements and a high-level team cultivation platform.

### Solution plan:

Based on the construction of intelligent education computing acceleration platform of Artificial Intelligence College of XIAN UNIVERSITY, and combined with the practical experience of similar customers before, siton Heli proposes a complete cluster solution of management node + computing node (several NVIDIA dgx-1) + storage + Infiniband network.





School of Artificial Intelligence

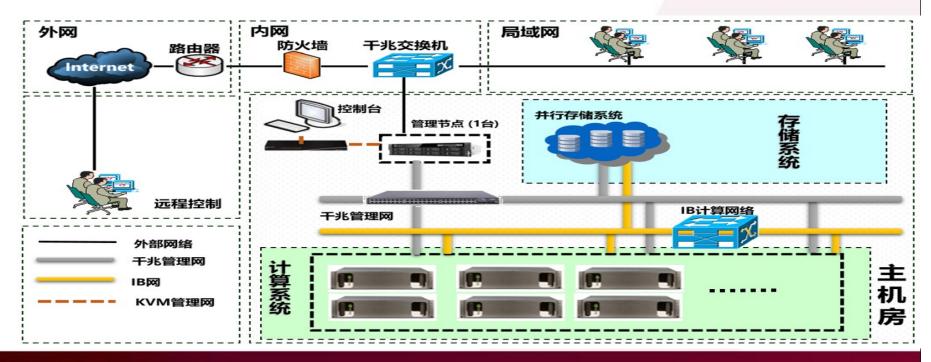
UNIVERSITY -AI computing accele and technology-a computing acceleration platform project

#### **NVIDIA DGX-1:**

- -The computing power can reach petaflops
- -8 xTesla V100 nvlink interconnection technology
- -NVIDIA CUDA core quantity 40960
- -Number of NVIDIA sensor cores 5120

Through the GPU cluster solution, siton Heli has successfully built a computing acceleration Pingsheng for XIAN UNIVERSITY









#### PING AN TECHNOLOGY - DGX-1

#### **Project background:**

Founded in 2008, PING AN TECHNOLOGY is a wholly-owned subsidiary of Ping An Group Guokang. Your company has branches in Shenzhen, Beijing, Shanghai, Chengdu and Nanjing. Ping An technology develops and operates key pinghao and services of PING AN TECHNOLOGY negative voice, which supports the efficient development of the group's insurance, banking, investment and Internet business. At the same time, it is also a technology incubator of Ping An group. It has strong cloud, artificial intelligence and big materials Research and development capabilities

In the financial industry, time is money, and millisecond determines profitWith lightning insight and decisive execution, profits can be made. The focus is on making informed decisions faster than competitors, which will ultimately be achieved by using big data, and obtaining analysis results faster is a big advantage. With the statistical calculation gradually approaching the limit, the financial industry is focusing on GPU, and banks and investment companies are gradually switching to NVIDIA GPU NVIDIA DGX-1 (the first system developed for in-depth and a-accelerated analysis in the world) to meet the real-time analysis needs, including fraud analysis, risk management and algorithmic transactions.



#### Core requirements:

1. In portfolio risk management, a trader must extract information and input it into a special system to perform advanced analysis and modeling. When calculating risk, a large number of calculations are needed, which usually takes all night to divide into "lines", and it is difficult to make adjustments in time with market changes. 2. Transaction execution involves figuring out how to find out the best price of a stock in the limit order book. Whether the trading time is hundreds of milliseconds or a minute from now, in the trading gap of more and more specific stocks, we all want to know when the stock price is the highest, now or a few seconds later.

#### Solution:

In response to the needs of users, siton Heli puts forward the NVIDIA DGX-1 super Thunderhead solution. With the help of advanced GPU and in-depth event processing technology, traders can perform arduous tasks such as data exploration, model development scoring and model consumption on the computing platform





#### PING AN TECHNOLOGY - DGX-1

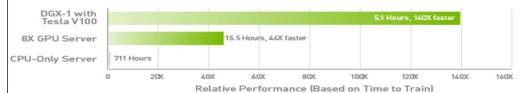
Secondly, in the process of trading execution, by mastering the quantitative data supported by the deep learning framework, we can understand the future trend of this threshold stock through the millions of trading data in the past. After the period training of massive data, we can make real-time reasoning on these data, and judge whether we should trade in a few hundred milliseconds, a second or a minute. This kind of intelligence cap improves the potential of algorithmic trading

#### NVIDIA DGX-1:

- -The computing power can reach 1 PetaFLOPS
- -8×Tesla V100 nvlink interconnection technology
- -NVIDIA a CUDA core quantity 40960
- -Number of NVIDIA sensor cores 5120

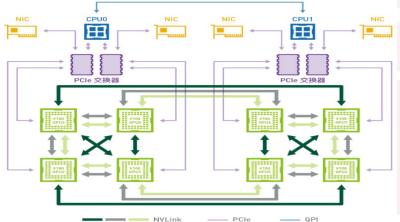
Nvlink is a high bandwidth and low energy consumption interconnection technology. With this technology, the interconnection between nvd|agpu and the same generation GPU or other devices in the node can be realized. The total bandwidth of each GPU can reach 300gb / 5, which is about 9 times of the current interconnection of pcle gen3x16 and the hybrid cube GPU topology of DGX-1 orange. The highest bandwidth can be achieved between a group of 8 Tesla v100 of data exchange.

#### NVIDIA DGX-1 Delivers 140X Faster Deep Learning Training



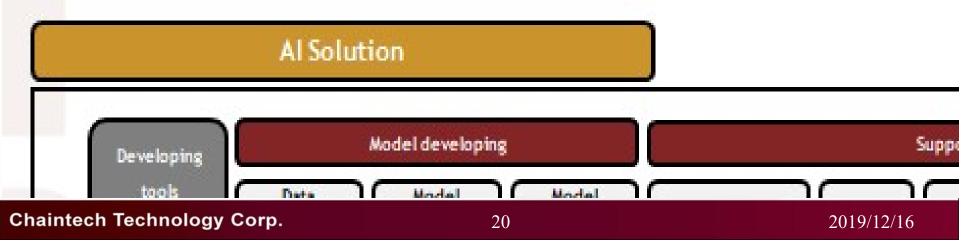
Workload: ResNet-50, 90 epochs to solution | CPU Server: Dual Xeon E5-2699v4, 2.6GHz





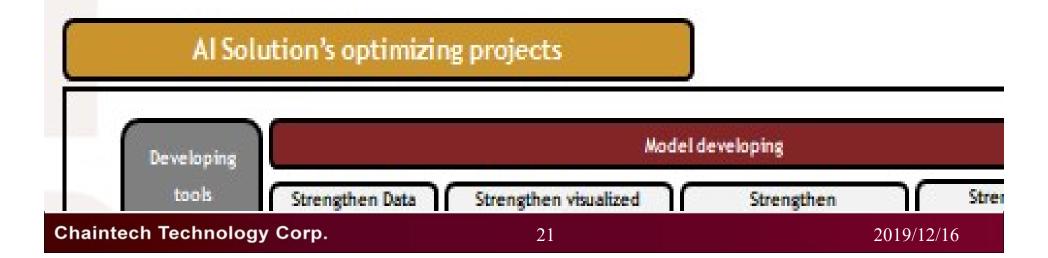
# 2019's Achievement

- Jointly launch a new Al solution, which comprises high-end server management systems based on Kubernetes and Hadoop and deve subsidiary company SitonHoly.
- With powerful, specialized and competitive management systen have created differentiation advantages in among of our compe hardware's sale volume and profit margin and gradually show be



# 2020's Plan

- Continue to strengthen the competitiveness of the AI solution, t advanced players and to increase the sales and profit margin.
- Cut into the Al market in Mainland China, keep integrating key r business opportunities of applications by segment.





# **Product Information**

# **SITONHOLY Software product**

# 1. SITONHOLY SCM artificial intelligence training platform v2.0

- Unified management of GPU resources to improve the utilization rate of GPU resources
- Data parallel training with multiple GPUs
- Based on tensorflow, mxnet, Python and other mainstream deep learning frameworks, through the combination of self-study services and docker container technology, it helps users to host deep learning training jobs and cluster management

SCM for large-scale heterogeneous computing infrastructure management, can realize the automation of deep learning computing resource management, scheduling and application, can be widely used in education, scientific research, remote sensing, medical, energy, government and other industries, can greatly improve the efficiency of computing infrastructure resource utilization, reduce the total cost of ownership of the data center, and improve the efficiency of artificial intelligence R & D innovation.



# 2. SITONHOLY SMP heterogeneous resource monitoring platform

## Monitoring introduction:

- 1. CPU consumption (including proportion)
- 2. System memory consumption (including proportion), surplus

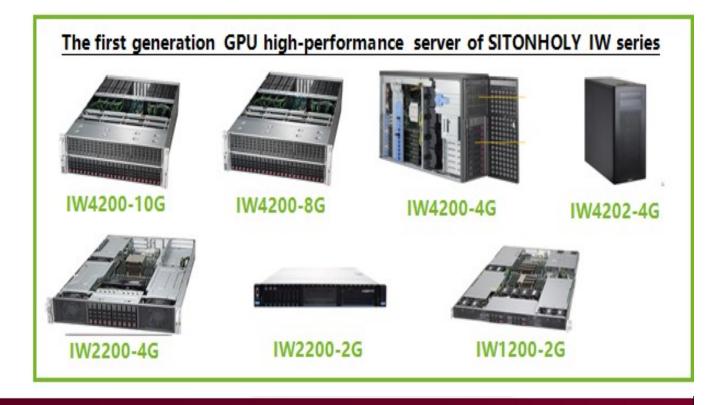


# **SITONHOLY Hardware products**

# 1. DGX products



# 2. SITONHOLY GPU server





# Colorful GeForce RTX 2080 SUPER Gaming ES







	GPU	GeForce RTX 2080 SUPER	
Chipset	Manufacturing Process	12nm	
	CUDA cores	3072	
	Base/Boost Clock	1650MHz/1815MHz	
Core Clocks	(Turbo Model) Base/Boost Clock	N/A	
	Buswidth	256Bit	
	Memory Clock	15.5Gbps	
Memory	Memory Config	8GB	
Clocks	Memory Interface	GDDR6	
	Memory Bandwidth	496GB/S	
	Video Output	3*DP+1*HDMI	
Display and	Maximum Digital Resolution*	7680x4320	
Connectors	PCI Express	3.0	
	NVLink/SLI	Yes	
	Maximum GPU Temperature	89 C	
Thermal and Power	Graphics Card Power	250W	
Specs	Power Phase	8+2	
	Power connector	8+8Pin	
	Туре	2*90+1*80mm	
Cooling	Intelligent star-stop fans	N	
	Heatpipe size & Q' ty	3*φ8	
25 451	Fan Power Connector	DirectX 12	
3D API	DirectX	OpenGL 4/5	
	OpenGL	Real-Time Ray Tracing, Ansel, GPU Boost	
Others	Supported NV Technologies	Over Dual slot	
	Form Factor	310*126*53mm	



# **Colorful GeForce RTX 2070 SUPER Gaming ES**



	GPU	GeForce RTX 2070 SUPER
Chipset	Manufacturing Process	12nm
	CUDA cores	2560
	Base/Boost Clock	1605/1770MHz
Core Clocks	(Turbo Model) Base/Boost Clock	N/A
	Buswidth	256Bit
	Memory Clock	14Gbps
Memory	Memory Config	8GB
Specs	Memory Interface	GDDR6
	Memory Bandwidth	448GB/S
Diamlay	Video Output	3*DP 1.4 +1*HDMI 2.0
Display and Connector	Maximum Digital Resolution*	7680x4320@60Hz
S	PCI Express	3.0
_	NVLink/SLI	YES
Thermal	Maximum GPU Temperature	88 C
and Power	Graphics Card Power	215W (NV)
Specs	Power Phase	8+2
	Power connector	8+8Pin
	Type	3 * Fan (1*80+2*90mm)
Cooling	Intelligent star-stop fans	YES
	Heatpipe size & Q' ty	3*φ8
	Fan Power Connector	8-pin, PWM
3D API	DirectX	DirectX12
<b>35</b> 7 1	OpenGL	OpenGL 4/5
	Supported NV Technologies	Real-Time Tracing, Ansel ,GPU Boost
Others	Form Factor	Dual Slot
Others	Dimensions	310*126*53mm
	Back Plate	Yes



# iGame GeForce GTX 1660 Ti Ultra 6G







	GPU	GeForce GTX 1660 Ti
Chipset	Manufacturing Process	12nm
	CUDA cores	1536
	Base/Boost Clock	1500MHz/1770MHz
Core Clocks	(Turbo Model) Base/Boost Clock	1500MHz/1845MHz
	Buswidth	192Bit
	Memory Clock	12Gbps
Memory	Memory Config	6GB
Specs	Memory Interface	GDDR6
	Memory Bandwidth	288GB/S
Display	Video Output	DP+HDMI+DVI
and Connector	Maximum Digital Resolution*	7680x4320@60Hz
S	PCI Express	3.0
	SLI	NO
Thermal	Maximum GPU Temperature	89°C (NV)
and Power Specs	Graphics Card Power	120W
Specs	Power connector	8 PIN
	Туре	3*90mm Fan
Cooling	Intelligent star-stop fans	NO
- Cooming	Heatpipe size & Q' ty	Ф6*2
	Fan Power Connector	4 PIN PWM
3D API	DirectX	DirectX12
	OpenGL	OpenGL 4/5
	Supported NV Technologies	Ansel ,GPU Boost
Others	Form Factor	Dual Slot
Others	Dimensions	310*126*42mm
	Back Plate	YES



## iGame GeForce RTX 2080 Ti Advanced







	GPU	GeForce RTX 2080 Ti
Chipset	Manufacturing Process	12nm
-	CUDA cores	4352
Core	Base/Boost Clock	1350/1635MHz
Clocks	One-key OC	N/A
	Memory Clock	14Gbps
Memory	Memory Config	11GB
Specs	Memory Interface	GDDR6
	Memory Bandwidth	616GB/S
		3*DP 1.4
Dienloy	Video Output	1*HDMI 2.0
Display and		1*USB Type-c
Connecto	Maximum Digital	7680x4320@60Hz
rs	Resolution*	7080x <del>4</del> 320@00112
13	PCI Express	3.0
	SLI	Yes
Thermal	Maximum GPU	89°C (NV)
and	Temperature	
Power	Graphics Card Power	250W (NV)
Specs	Power supply	8+8pin
	Power Phase	13+3
	Туре	3 * Fan (90mm)
Cooling	Intelligent start-stop fans	YES
Cooming	Heatpipe size & Q'ty	5*φ8
	Fan Power Connector	8pin, PWM
3D API	DirectX	DirectX12
<b>3D</b> / <b>H</b> I	OpenGL	OpenGL 4/5
	Supported NV	Real-Time Tracing,
	Technologies	Ansel ,GPU Boost
Othors	Form Factor	Over Dual Slot
Others	Dimensions	304*118*52mm
	Back Plate	YES

